

## 0.8% Accuracy, Voltage Detector with Delay Function

NO.EA-306-130326

### OUTLINE

The RP300x Series are CMOS-based voltage detector (VD) ICs with a built-in output delay circuit. Internally, a single IC consists of a voltage reference unit, a comparator, a resistor net for setting detector threshold, a manual reset circuit, an output delay circuit and an output driver transistor.

The RP300x Series are available in internally fixed detector threshold type. When the  $V_{DD}$  voltage becomes lower than the preset voltage, the RP300xxxxA/C generates a “L” reset signal and the RP300xxxxB (custom IC<sup>\*1</sup>) generates a “H” reset signal. The detector threshold accuracy is as high as  $\pm 1.0\%$  when  $-V_{SET}^{*2} < 1.7V$  and  $\pm 0.8\%$  when  $1.7V \leq -V_{SET}$ .

The reset output signal remains asserted for 50ms, 100ms (custom IC) or 200ms after the  $V_{DD}$  voltage rises above the threshold voltage or when manual reset is canceled. The RP300x Series are designed to ignore fast transients on the  $V_{DD}$  pin. The output delay time accuracy is as high as  $\pm 5.0\%$ .

The RP300x Series are available in an Nch open drain output type or in a CMOS output type.

The RP300x Series are offered in an ultra-small DFN(PLP)1010-4B package or in a SOT-23-5 package.

<sup>\*1</sup> For more information about a custom IC, please contact our sales representatives.

<sup>\*2</sup>  $-V_{SET}$  is defined as a preset detector threshold.

### FEATURES

- Supply Current ( $I_{SS}$ ) .....Typ. 0.95 $\mu$ A ( $-V_{SET}=3.08V$ ,  $V_{DD}=3.18V$ )
- Operating Voltage Range ( $V_{DD}$ ) .....0.72V to 5.50V (25°C)
- Detector Threshold Range ( $-V_{DET}$ ) .....1.1V, 2.32V, 2.63V, 2.7V, 2.8V, 2.93V, 3.08V, 4.38V, 4.6V
- Detector Threshold Accuracy ..... $\pm 1.0\%$  ( $-V_{SET} < 1.7V$ ),  $\pm 0.8\%$  ( $1.7V \leq -V_{SET}$ )
- Detector Threshold Temperature Coefficient .....Typ.  $\pm 50$ ppm/°C
- Released Output Delay Time ( $t_{DELAY}$ ) .....Typ. 50ms, 100ms (custom IC), 200ms
- Released Output Delay Time Accuracy ..... $\pm 5\%$  (25°C),  $\pm 15\%$  (-40°C to 85°C)
- Package .....DFN(PLP)1010-4B, SOT-23-5
- Output Type .....Nch Open Drain output, CMOS Output
- Reset Signal .....Active-low, Active-high (custom IC)

### APPLICATIONS

- Voltage monitoring for handheld communication equipment, camera and VCRs.
- Voltage monitoring for battery-powered equipment

## BLOCK DIAGRAMS

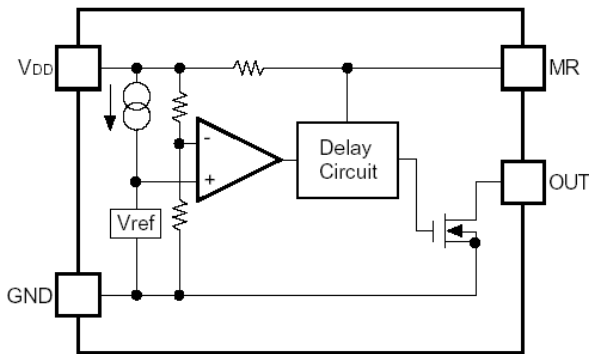


Figure 1. RP300xxxxA/B (Nch Open Drain Output)

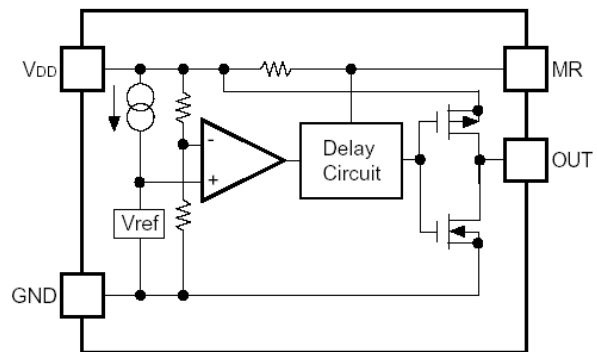


Figure 2. RP300xxxxC (CMOS Output)

## SELECTION GUIDE

With the RP300x Series, the detector threshold, the package type, the released output delay time and the output type are user-selectable options.

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
RP300Kxxy*(z)-TR	DFN(PLP)1010-4B	10,000pcs	Yes	Yes
RP300Nxxy*(z)-TR-FE	SOT-23-5	3,000pcs	Yes	Yes

xx: Specify  $-V_{SET}$  from 1.1V(11), 2.32V(23), 2.63V(26), 2.7V(27), 2.8V(28), 2.93V(29), 3.08V(30), 4.38V(43), 4.6V(46).

z: If  $-V_{SET}$  includes the 3<sup>rd</sup> digit, indicate the digit of 0.01V.  
 Ex. If  $-V_{SET}$  is 2.63V, indicate as RP300x26xx3-TR-x.

y: Specify the released output delay time.

- (A) 50ms
- (B) 100ms (custom IC)
- (D) 200ms

\*: Specify the output type.

- (A) Nch Open Drain Output
- (B) Nch Open Drain Inverting Output (custom IC)
- (C) CMOS Output

## PIN CONFIGURATIONS

• DFN(PLP)1010-4B

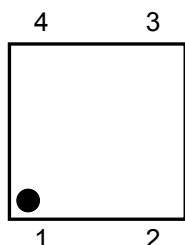


Figure 3. Top View

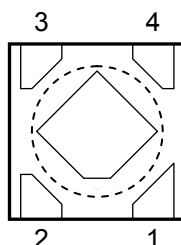


Figure 4. Bottom View

• SOT- 23-5

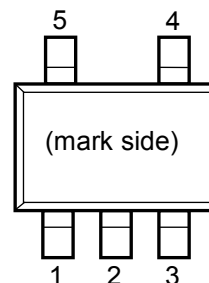


Figure 5. Mark Side

## PIN DESCRIPTION

### RP300K: DFN(PLP)1010-4B

Pin No.	Symbol	Pin Description
1	OUT	Output Pin RP300xxxxA/C: asserts an active-low reset signal when a voltage drops below the detector threshold. RP300xxxxB: asserts an active-high reset signal when a voltage drops below the detector threshold. (custom IC)
2	MR	Manual Reset Input Pin: active-low
3	GND	Ground Pin
4	V <sub>DD</sub>	Input Pin

The tab on the bottom of the package enhances thermal performance and is electrically connected to GND (substrate level). It is recommended that the tab be connected to the ground plane on the board. If not, the tab can be left open.

### RP300N: SOT-23-5

Pin No.	Symbol	Description
1	MR	Manual Reset Input Pin: active-low
2	GND	Ground Pin
3	NC	No Connection
4	OUT	Output Pin RP300xxxxA/C: asserts an active-low reset signal when a voltage drops below the detector threshold. RP300xxxxB: asserts an active-high reset signal when a voltage drops below the detector threshold. (custom IC)
5	V <sub>DD</sub>	Input Pin

## ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating	Unit	
$V_{IN}$	Input Voltage	6.0	V	
OUT	Output Voltage (Nch Open Drain Output)	-0.3 to 6.0	V	
	Output Voltage (CMOS Output)	-0.3 to $V_{DD} + 0.3$		
MR	Manual Reset Pin	-0.3 to $V_{DD} + 0.3$	V	
$I_{OUT}$	Output Current	20	mA	
$P_D$	Power Dissipation (Standard Land Pattern) <sup>*3</sup>	DFN(PLP)1010-4B	400	mW
		SOT-23-5	420	
$T_a$	Operating Temperature Range	-40 to +85	°C	
$T_{stg}$	Storage Temperature Range	-55 to +125	°C	

<sup>\*3</sup> Refer to the next page for detailed information about Power Dissipation.

### ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

### RECOMMENDED OPERATING CONDITIONS (ELECTRICAL CHARACTERISTICS)

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

## POWER DISSIPATION (DFN(PLP)1010-4B)

Power Dissipation ( $P_D$ ) of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement.

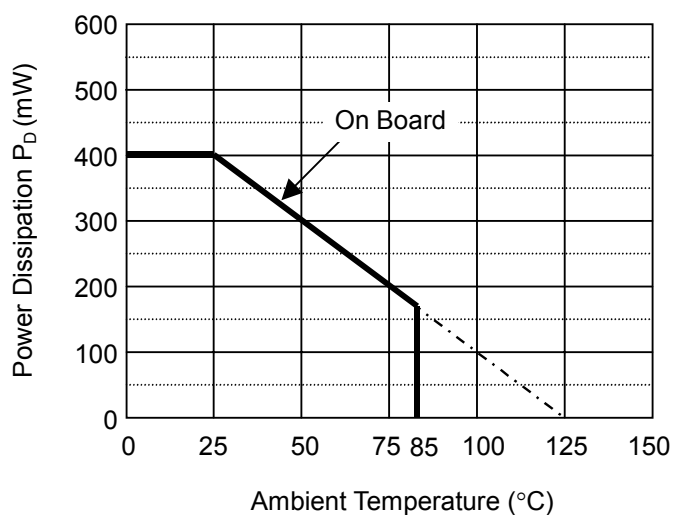
### Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind Velocity=0m/s)
Board Material	Glass Cloth Epoxy Plastic (Double-sided)
Board Dimensions	40mm x 40mm x 1.6mm
Copper Ratio	Top side: Approx. 50%, Back side: Approx. 50%
Through-holes	$\phi$ 0.54mm x 24pcs

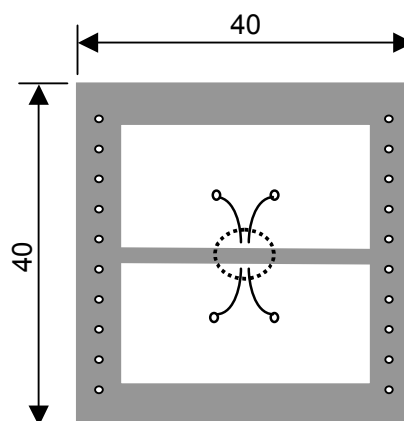
### Measurement Result:

( $T_a=25^\circ\text{C}$ ,  $T_{j\text{max}}=125^\circ\text{C}$ )


	Standard Land Pattern
Power Dissipation	400mW
Thermal Resistance	$\theta_{ja} = (125-25^\circ\text{C})/0.4\text{W} = 250^\circ\text{C/W}$
	$\theta_{jc} = 67^\circ\text{C/W}$



**Power Dissipation**



**Measurement Board Pattern**

 IC Mount Area (Unit : mm)

## POWER DISSIPATION (SOT-23-5)

Power Dissipation ( $P_D$ ) of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement. This data is taken from SOT-23-6.

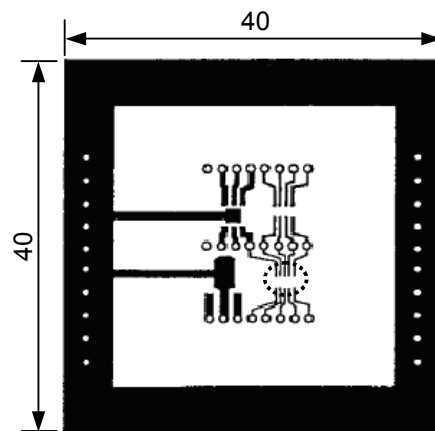
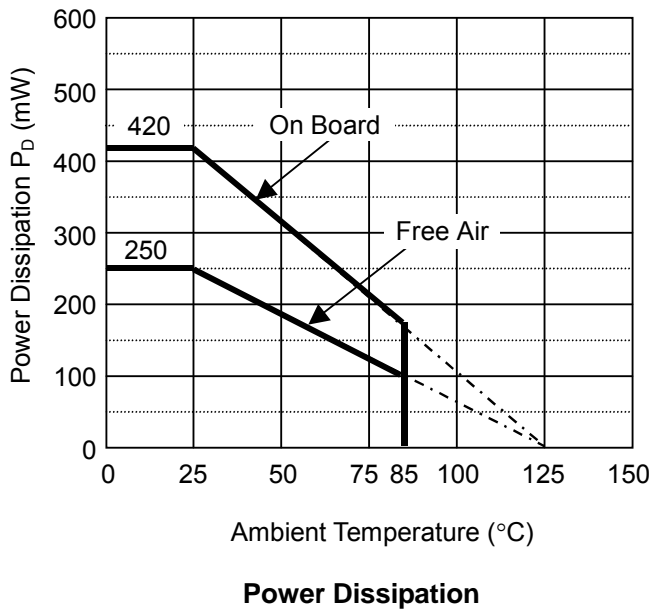
### Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind Velocity=0m/s)
Board Material	Glass Cloth Epoxy Plastic (Double-sided)
Board Dimensions	40mm x 40mm x 1.6mm
Copper Ratio	Top side: Approx. 50%, Back side: Approx. 50%
Through-holes	$\phi$ 0.5mm x 44pcs

### Measurement Result:

( $T_a=25^\circ\text{C}$ ,  $T_{j\text{max}}=125^\circ\text{C}$ )

	Standard Land Pattern	Free Air
Power Dissipation	420mW	250mW
Thermal Resistance	$\theta_{ja} = (125-25^\circ\text{C})/0.42\text{W} = 238^\circ\text{C/W}$	400 $^\circ\text{C/W}$



Measurement Board Pattern

 IC Mount Area (Unit: mm)

## ELECTRICAL CHARACTERISTICS

The specifications surrounded by   are guaranteed by Design Engineering at  $-40^{\circ}\text{C} \leq T_a \leq 85^{\circ}\text{C}$ .

### RP300x Series

( $T_a=25^{\circ}\text{C}$ )

Symbol	Item	Conditions	Min.	Typ.	Max.	Unit	
$-V_{\text{DET}}^{*4}$	Detector Threshold ( $T_a = 25^{\circ}\text{C}$ )	$-V_{\text{SET}}^{*4} < 1.7\text{V}$	$\times 0.99$		$\times 1.010$	V	
		$1.7\text{V} \leq -V_{\text{SET}}$	$\times 0.992$		$\times 1.008$	V	
	Detector Threshold ( $-40^{\circ}\text{C} \leq T_a \leq 85^{\circ}\text{C}$ )	$-V_{\text{SET}} < 1.7\text{V}$	<span style="border: 1px solid black; padding: 0 2px;"><math>\times 0.982</math></span>		<span style="border: 1px solid black; padding: 0 2px;"><math>\times 1.018</math></span>	V	
		$1.7\text{V} \leq -V_{\text{SET}}$	<span style="border: 1px solid black; padding: 0 2px;"><math>\times 0.984</math></span>		<span style="border: 1px solid black; padding: 0 2px;"><math>\times 1.016</math></span>	V	
$I_{\text{SS1}}$	Supply Current 1	$V_{\text{DD}} = -V_{\text{SET}} - 0.1\text{V}$ , $I_{\text{OUT}} = 0\text{A}$			3.2	$\mu\text{A}$	
$I_{\text{SS2}}$	Supply Current 2	$V_{\text{DD}} = -V_{\text{SET}} + 0.1\text{V}$ , $I_{\text{OUT}} = 0\text{A}$			3.1	$\mu\text{A}$	
$V_{\text{DD}}$	Operating Voltage	$T_a = 25^{\circ}\text{C}$	0.72		5.5	V	
		$-40^{\circ}\text{C} \leq T_a \leq 85^{\circ}\text{C}$	<span style="border: 1px solid black; padding: 0 2px;">0.80</span>		<span style="border: 1px solid black; padding: 0 2px;">5.5</span>	V	
$I_{\text{OUT}}$	Output Current (Driver Output Pin)	Nch $V_{\text{DD}} = -V_{\text{SET}} - 0.1\text{V}$ $V_{\text{DS}} = 0.3\text{V}$	$-V_{\text{SET}} \geq 1.1\text{V}$	0.45			mA
			$-V_{\text{SET}} \geq 1.6\text{V}$	2.5			mA
			$-V_{\text{SET}} \geq 2.7\text{V}$	4.8			mA
		Nch Inverting <sup>*5</sup> $V_{\text{DD}} = -V_{\text{SET}} + 0.1\text{V}$ $V_{\text{DS}} = 0.3\text{V}$	$-V_{\text{SET}} \geq 1.1\text{V}$	0.45			mA
			$-V_{\text{SET}} \geq 1.4\text{V}$	2.5			mA
			$-V_{\text{SET}} \geq 2.5\text{V}$	4.8			mA
		Pch CMOS $V_{\text{DD}} = -V_{\text{SET}} + 0.1\text{V}$ $V_{\text{DS}} = -0.3\text{V}$	$-V_{\text{SET}} \geq 1.1\text{V}$	-0.15			mA
			$-V_{\text{SET}} \geq 1.6\text{V}$	-0.45			mA
			$-V_{\text{SET}} \geq 2.7\text{V}$	-0.8			mA
$I_{\text{LEAK}}$	Nch Driver Leakage Current	$V_{\text{DD}} = 5.5\text{V}$ $V_{\text{DS}} = 5.5\text{V}$	RP300xxxxA/C			<span style="border: 1px solid black; padding: 0 2px;">0.15</span>	$\mu\text{A}$
		$V_{\text{DD}} = -V_{\text{SET}} - 0.1\text{V}$ $V_{\text{DS}} = 5.5\text{V}$	RP300xxxxB <sup>*6</sup>				
$R_{\text{MR}}$	MR Pin Pull-up Resistance		0.21	0.45	0.90	M $\Omega$	
$V_{\text{IH}}$	MR Pin Input Voltage "H"	$V_{\text{DD}} \geq -V_{\text{SET}} + 0.1\text{V}$	<span style="border: 1px solid black; padding: 0 2px;">0.75</span> $\times V_{\text{DD}}$			V	
$V_{\text{IL}}$	MR Pin Input Voltage "L"	$V_{\text{DD}} \geq -V_{\text{SET}} + 0.1\text{V}$			<span style="border: 1px solid black; padding: 0 2px;">0.4</span>	V	
$t_{\text{DELAY}}^{*8}$	Released Output Delay Time	$V_{\text{DD}} = 0.8\text{V} \rightarrow$ $-V_{\text{SET}} + 1.0\text{V}$	RP300xxxAx	47.5	50	52.5	ms
			RP300xxxBx <sup>*7</sup>	95	100	105	
			RP300xxxDx	190	200	210	
		$-40^{\circ}\text{C} \leq T_a \leq 85^{\circ}\text{C}$	<span style="border: 1px solid black; padding: 0 2px;"><math>t_{\text{SET}}^{*8}</math></span> $\times 0.85$			<span style="border: 1px solid black; padding: 0 2px;"><math>t_{\text{SET}} \times</math></span> <span style="border: 1px solid black; padding: 0 2px;">1.15</span>	%
$\Delta V_{\text{DET}} / \Delta T_a$	Detector Threshold Temperature Coefficient	$-40^{\circ}\text{C} \leq T_a \leq 85^{\circ}\text{C}$		$\pm 50$		ppm/ $^{\circ}\text{C}$	

All test items listed under Electrical Characteristics are done under the pulse load condition ( $T_j \approx T_a = 25^{\circ}\text{C}$ ) except Detector Threshold Temperature Coefficient.

<sup>\*4</sup>  $V_{\text{DET}}$  is defined as an actual detector threshold and  $-V_{\text{SET}}$  is defined as a preset detector threshold.

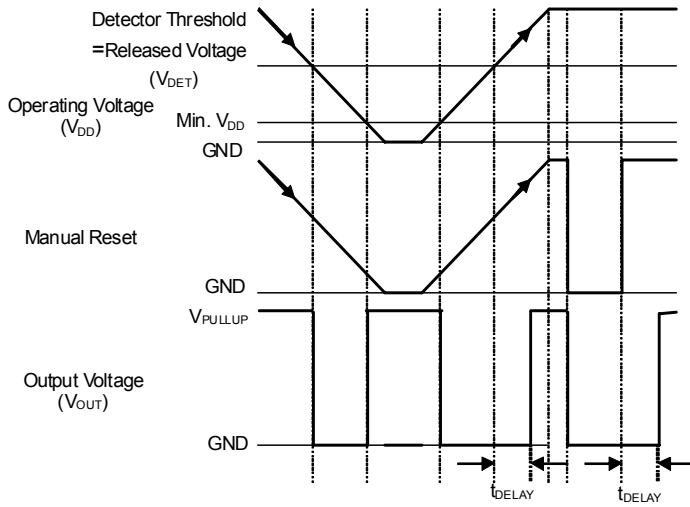
<sup>\*5</sup> Nch open drain inverting output type is only applicable to the RP300xxxxB which is a custom IC.

<sup>\*6</sup> The RP300xxxxB is a custom IC.

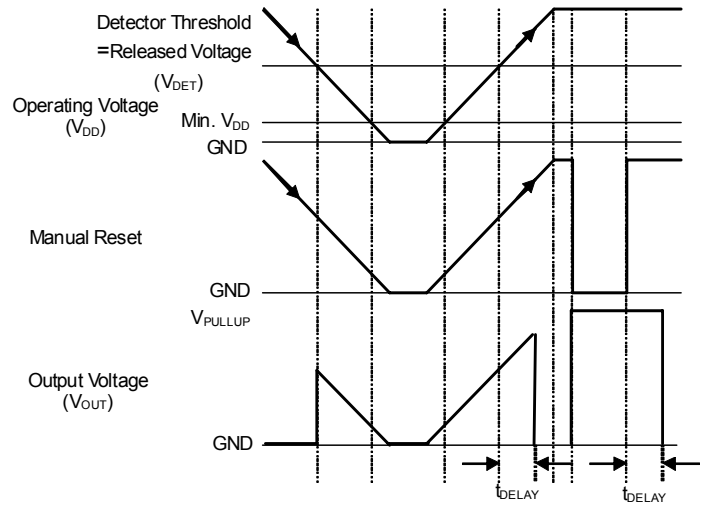
<sup>\*7</sup> The RP300xxxBx is a custom IC.

<sup>\*8</sup>  $t_{\text{DELAY}}$  is defined as an actual released output delay time and  $t_{\text{SET}}$  is defined as a preset released output delay time.

**TIMING CHART**



**Figure 6. RP300xxxxA/C**



**Figure 7. RP300xxxxB**

**Release Output Delay Time ( $t_{\text{DELAY}}$ )**

$t_{\text{DELAY}}$  is defined as follows.

1. Nch Open Drain Output

Release output delay time starts after the OUT pin is pulled up to 5.5V with a 470kΩ resistor, and the  $V_{\text{DD}}$  voltage is shifted from 0.8V to  $-V_{\text{SET}} + 1.0\text{V}$ . It ends when the output voltage reaches 1.0V.

2. Nch Open Drain Inverting Output (custom IC)

Release output delay time starts after the OUT pin is pulled up to 5.5V with a 470kΩ resistor, and the  $V_{\text{DD}}$  voltage is shifted from 0.8V to  $-V_{\text{SET}} + 1.0\text{V}$ . It ends when the output voltage reaches  $V_{\text{DD}}/2\text{V}$ .

3. CMOS Output

Release output delay time starts when the  $V_{\text{DD}}$  voltage is shifted from 0.8V to  $-V_{\text{SET}} + 1.0\text{V}$  and ends when the output voltage reaches  $V_{\text{DD}}/2\text{V}$ .

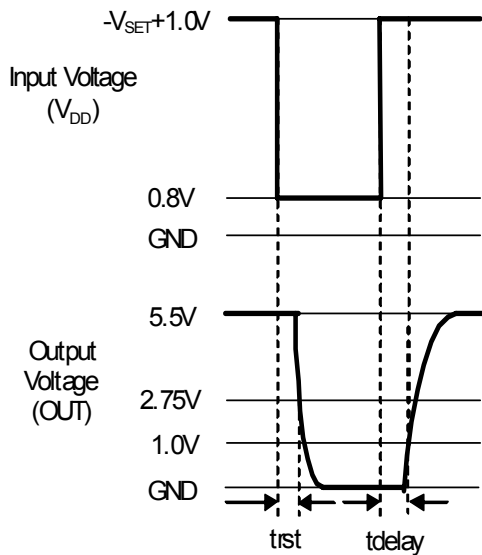


Figure 8. Nch Open Drain Output

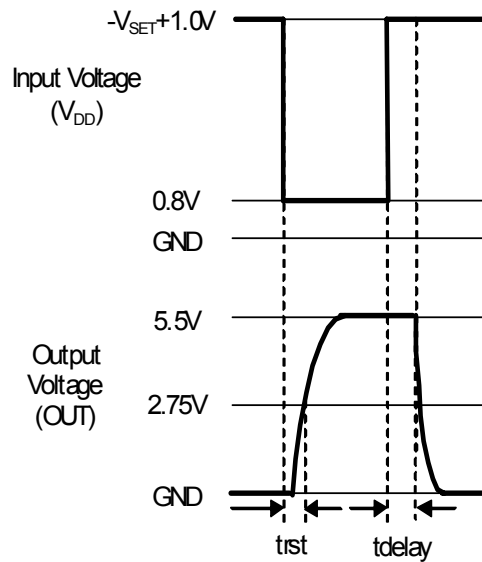


Figure 9. Nch Open Drain Inverting Output

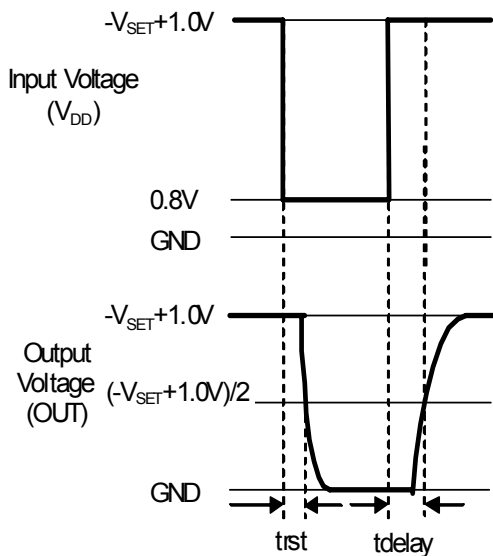


Figure 10. CMOS Output

## THEORY OF OPERATION

RP300xxxxA/C

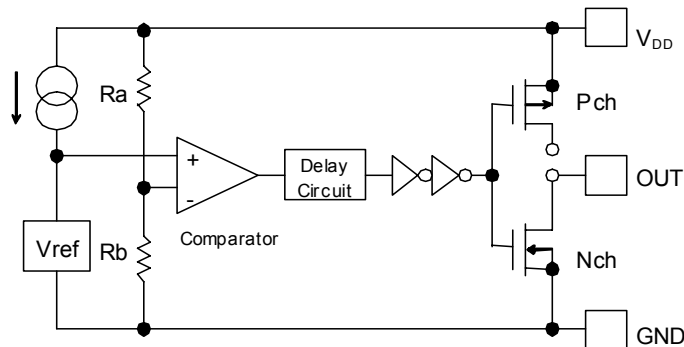


Figure 11. Block Diagram

- For CMOS Output, the Nch Tr. drain and the Pch Tr. drain are connected to the OUT pin inside the IC.
- For Nch Open Drain Output, the Nch Tr. drain is connected to the OUT pin inside the IC. Pull up the OUT pin or  $V_{DD}$  pin to the external voltage level.

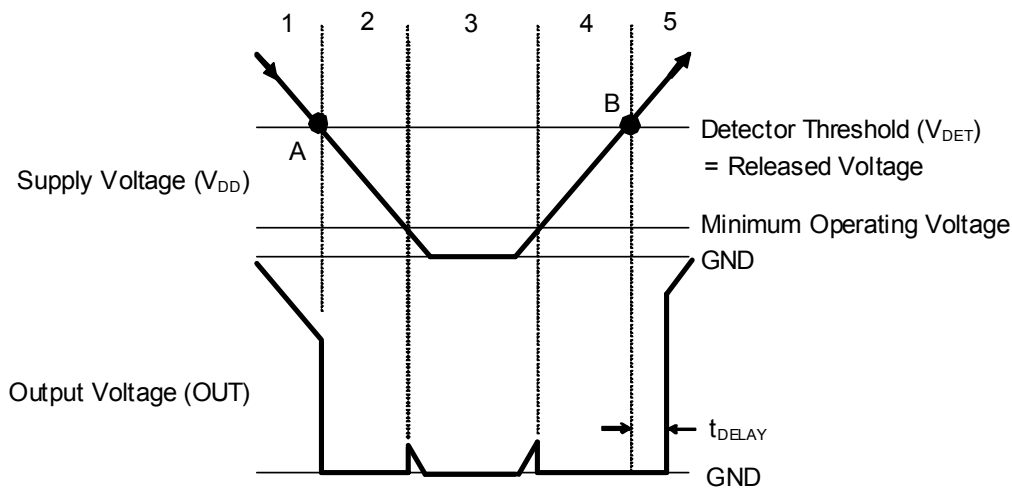


Figure 12. Timing Chart

1. The output voltage is equalized to the  $V_{DD}$  voltage (CMOS Output), or to the pull-up voltage (Nch Open Drain Output).
2. The  $V_{DD}$  voltage drops to the detector threshold (A point) which means  $V_{ref} \geq V_{DD} \times R_b / (R_a + R_b)$ . The comparator output shifts from “L” to “H” voltage and the output pin voltage will be equalized to the GND voltage.
3. If the  $V_{DD}$  voltage is lower than the minimum operating voltage, the output voltage becomes unstable.
4. The output pin voltage is equalized to the GND voltage.
5. The  $V_{DD}$  voltage becomes higher than the release voltage (B point) which means  $V_{ref} < V_{DD} \times R_b / (R_a + R_b)$ , and the comparator output shifts from “H” to “L” voltage, and the output pin voltage is equalized to the  $V_{DD}$  voltage (CMOS Output) or to the pull-up voltage (Nch Open Drain Output).

Note: There's no hysteresis between the  $V_{DD}$  voltage and the released voltage.

RP300xxxxB

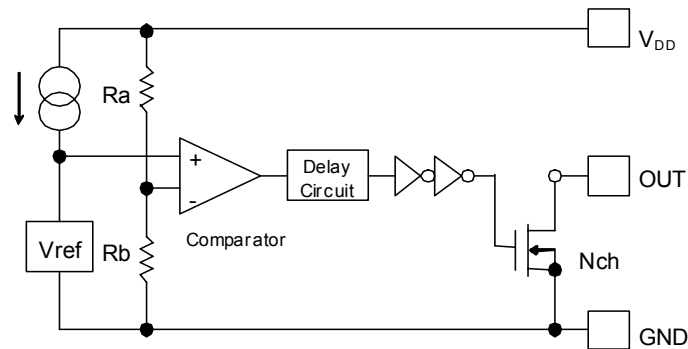


Figure 13. Block Diagram

- The Nch Tr. drain is connected to the OUT pin inside the IC. Pull up the OUT pin or V<sub>DD</sub> pin to the external voltage level.

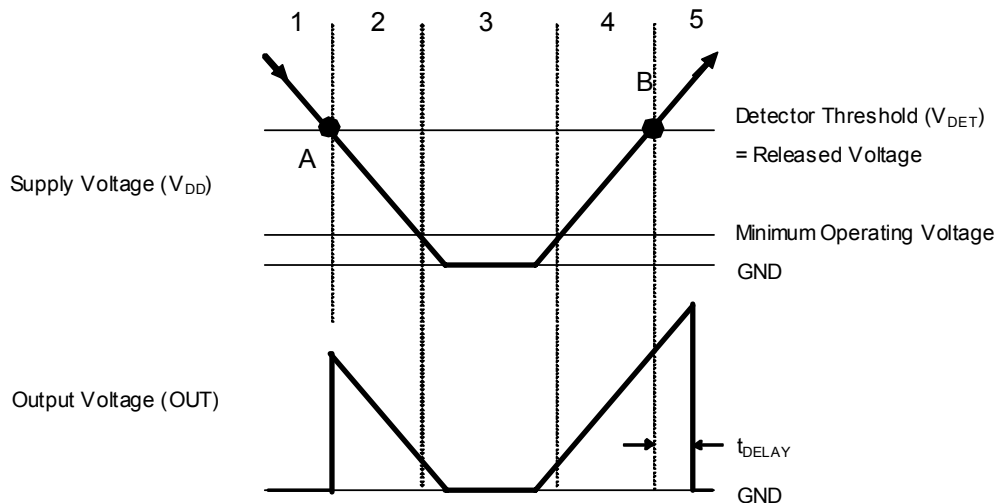


Figure 14. Timing Chart

1. The output voltage is equalized to the GND voltage.
2. The V<sub>DD</sub> voltage drops to the detector threshold (A point) which means  $V_{ref} \geq V_{DD} \times R_b / (R_a + R_b)$ . The comparator output shifts from “H” to “L” voltage and the output pin voltage shifts from the pull-up voltage to “L” voltage.
3. If the V<sub>DD</sub> voltage is lower than the minimum operating voltage, the output voltage becomes unstable.
4. The output voltage is equalized to the pull-up voltage.
5. The V<sub>DD</sub> voltage becomes higher than the release voltage (B point) which means  $V_{ref} < V_{DD} \times R_b / (R_a + R_b)$ . The comparator output shifts from “L” to “H” voltage, and the output pin voltage is equalized to the GND voltage.

Note: There’s no hysteresis between the V<sub>DD</sub> voltage and the released voltage.

**Detector Operation vs. Glitch Input Voltage**

The RP300x Series have built-in rejection of fast transients on the  $V_{DD}$  pins. The rejection of transients depends on both the duration and the amplitude of the transient. The amplitude of the transient is measured from the bottom of the transient to the negative threshold voltage of the RP300x Series, as shown in Figure 16.

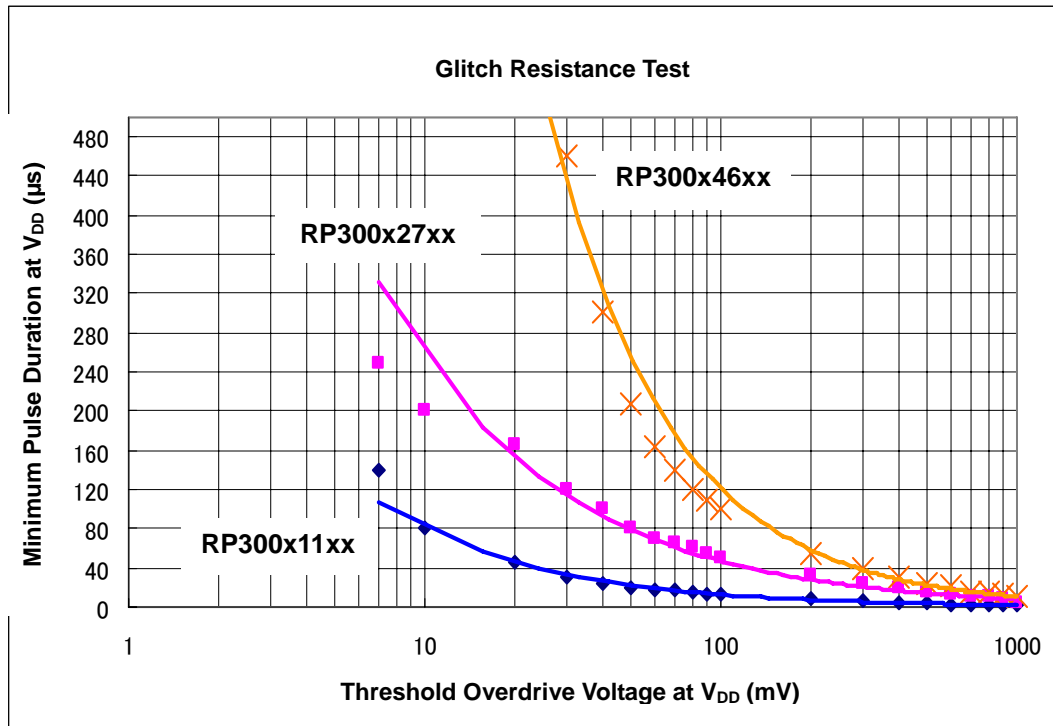


Figure 15. Minimum Pulse Duration at  $V_{DD}$  vs. Overdrive Voltage at  $V_{DD}$

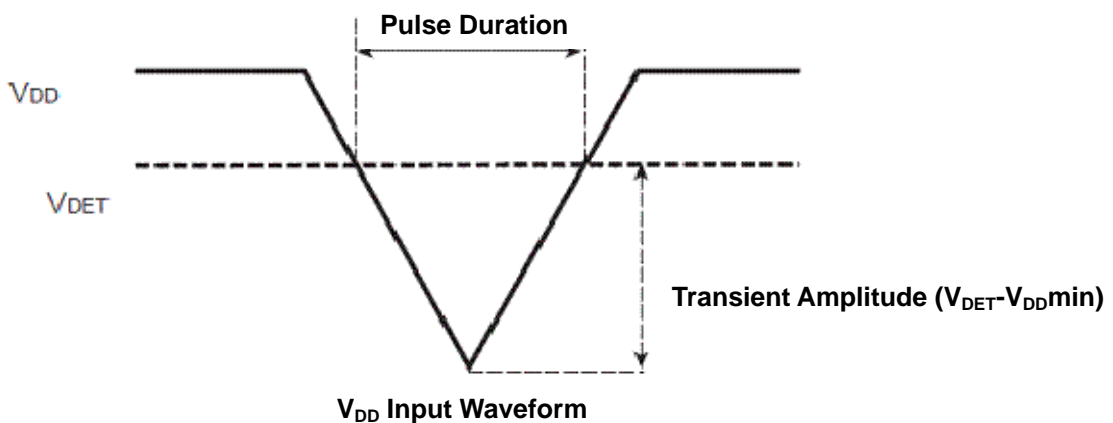


Figure 16. Voltage Transient Measurement

The RP300x Series do not respond to transients that are fast duration/ low amplitude or long duration/ small amplitude. Figure 15 shows the relationship between the transient amplitude and duration needed to trigger a reset. Any combination of duration and amplitude above the curve generates a reset signal.

TEST CIRCUITS

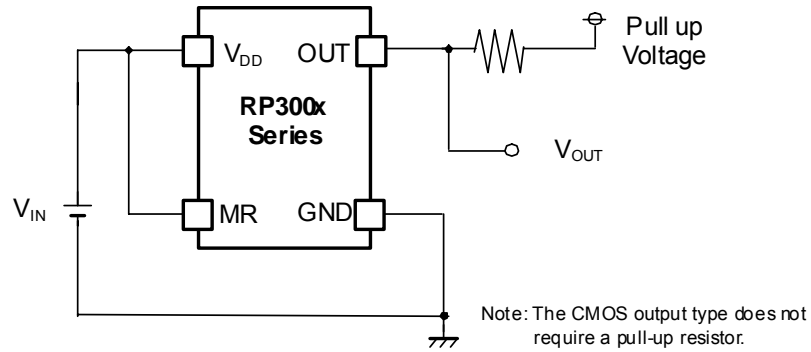


Figure 17. Basic Test Circuit

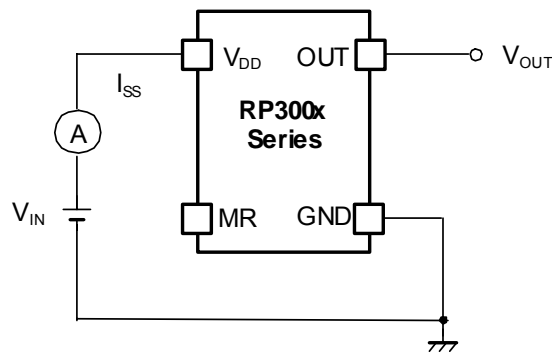


Figure 18. Test Circuit for Supply Current

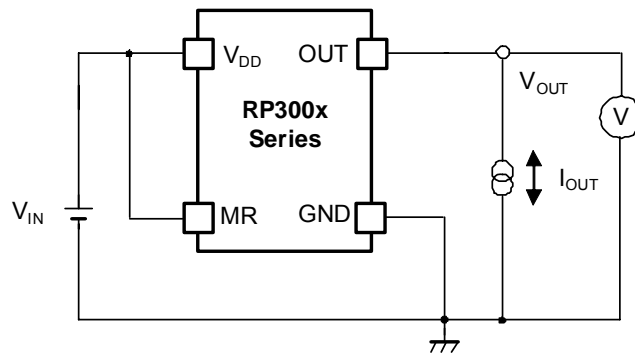


Figure 19. Test Circuit for Output Current

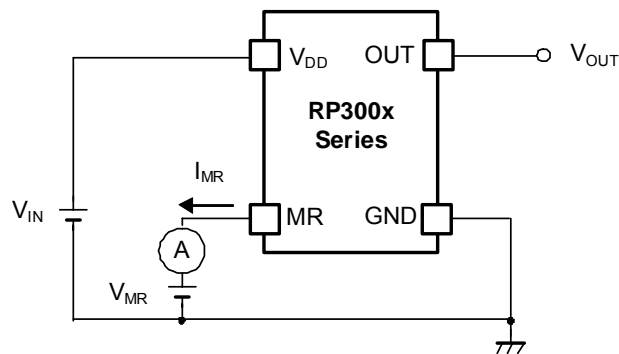
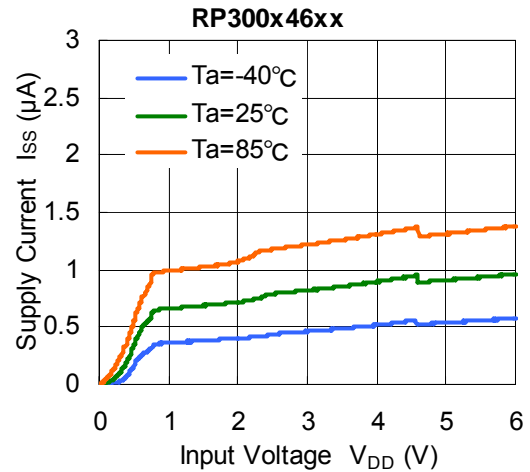
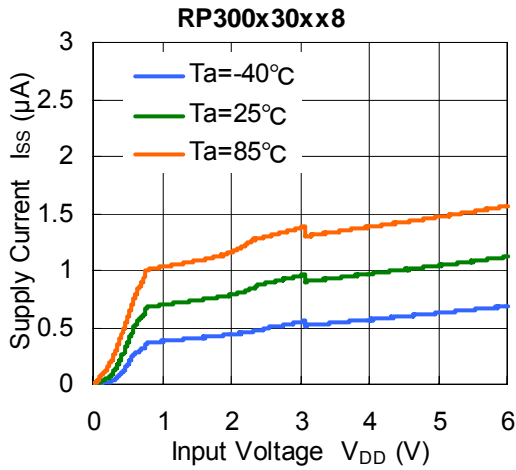
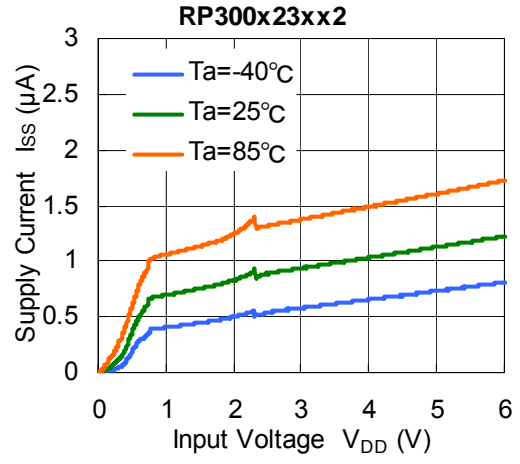
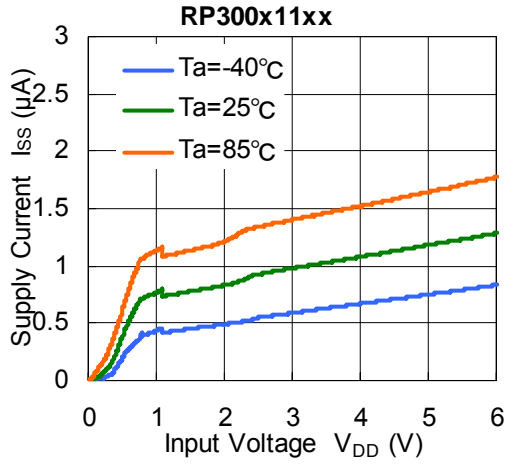


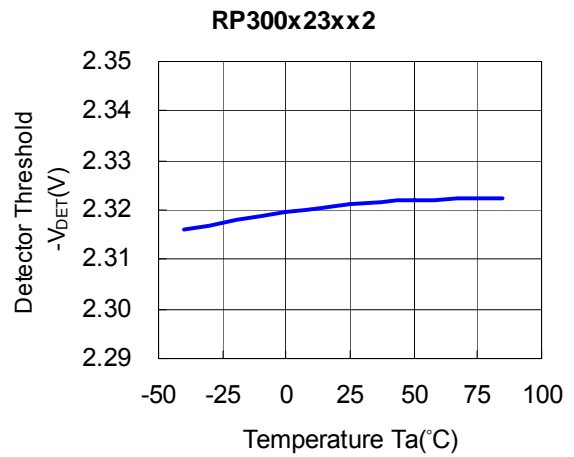
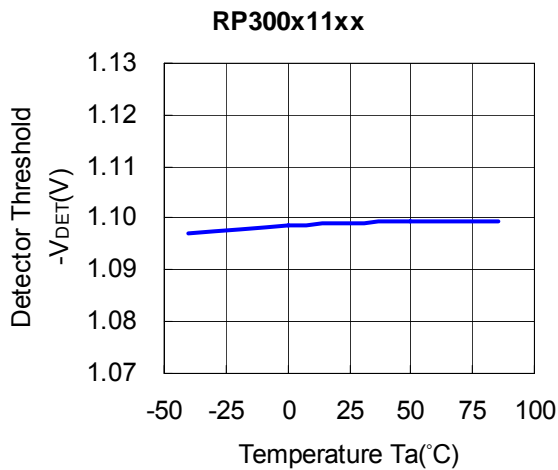
Figure 20. MR Pin Pull-up Resistor

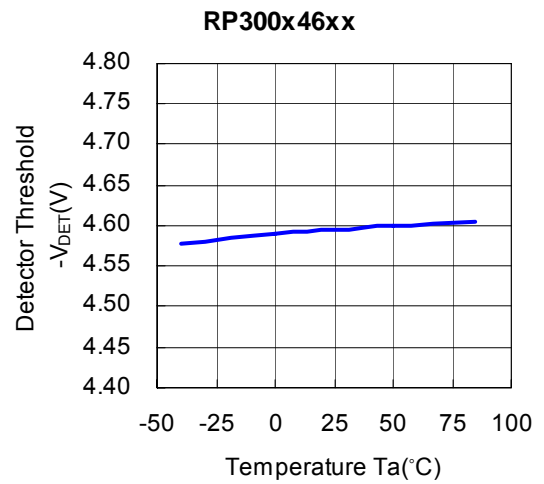
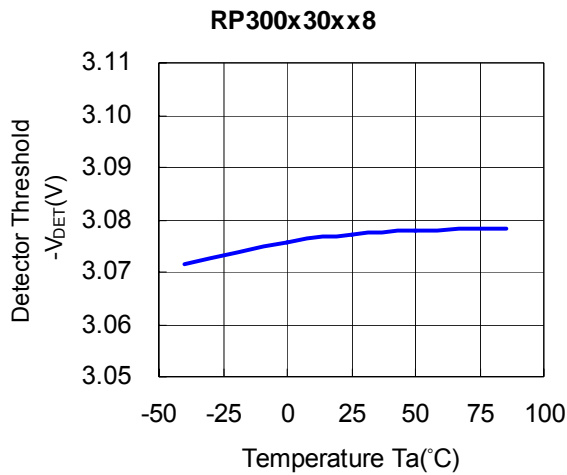
## TYPICAL CHARACTERISTICS

### 1) Supply Current vs. Input Voltage

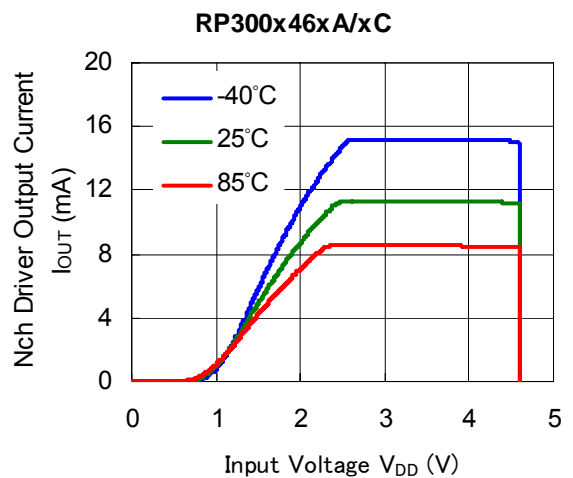
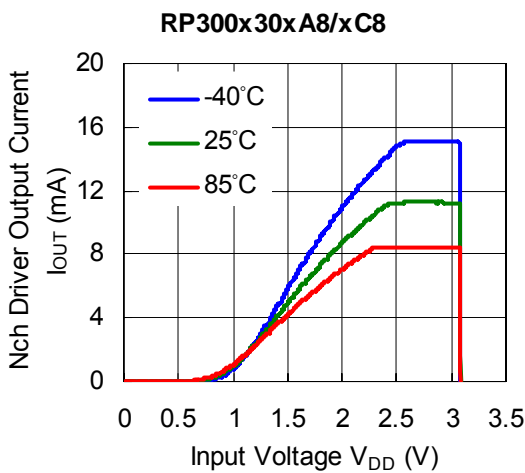
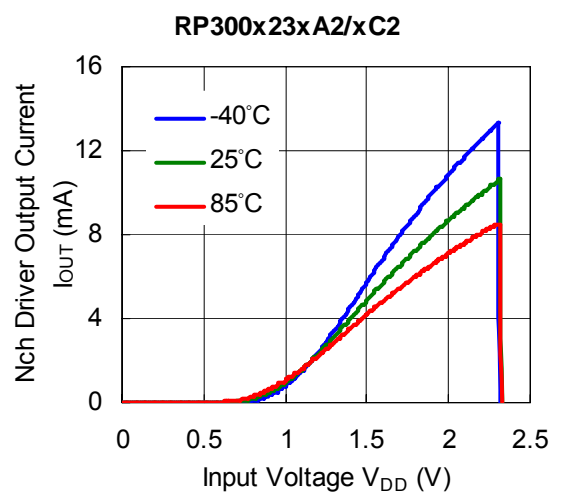
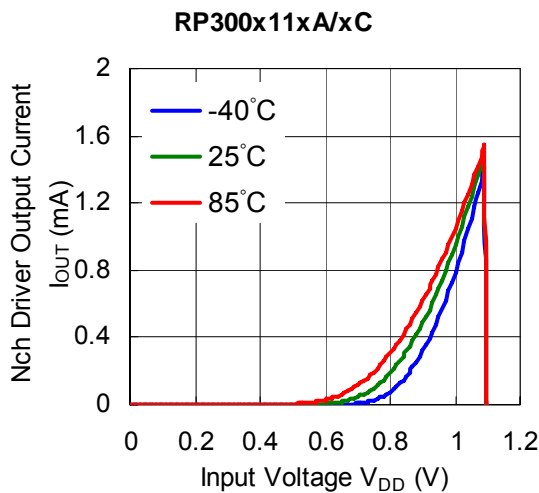


### 2) Detector Threshold vs. Temperature

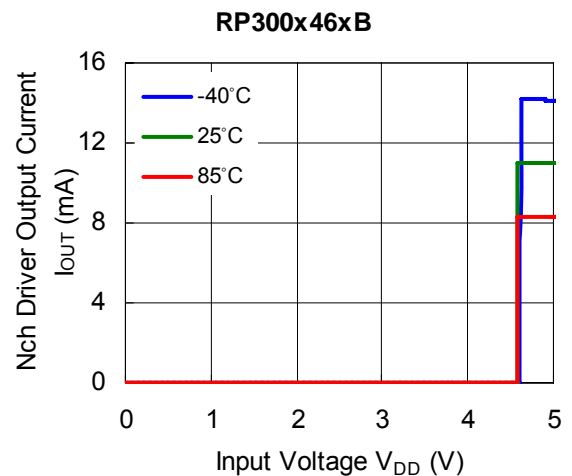
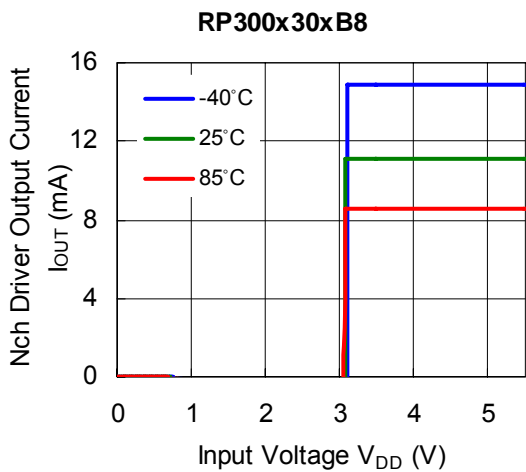
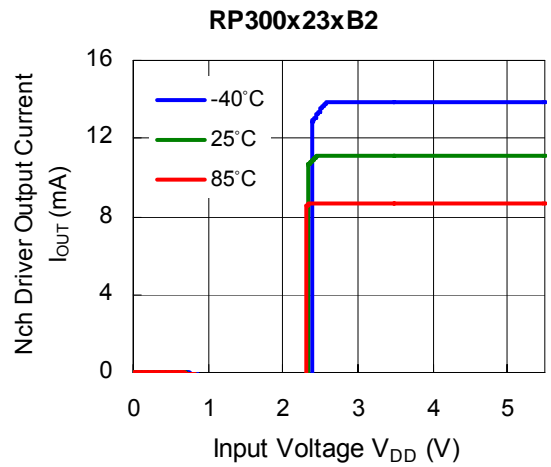
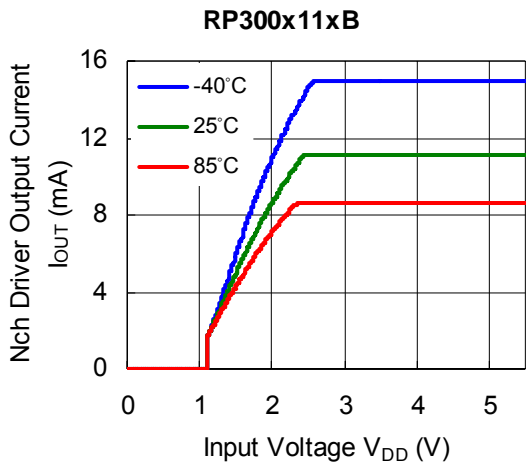




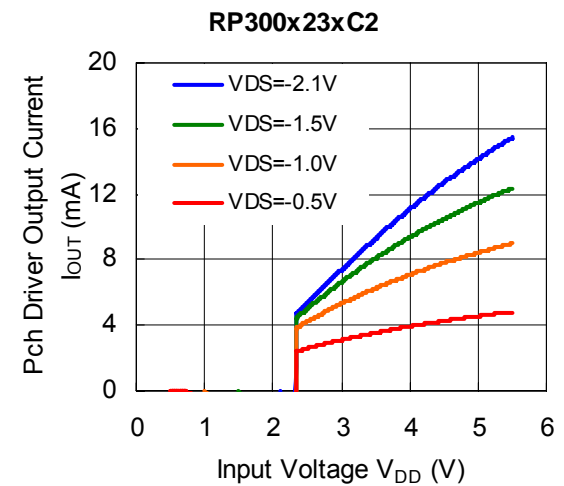
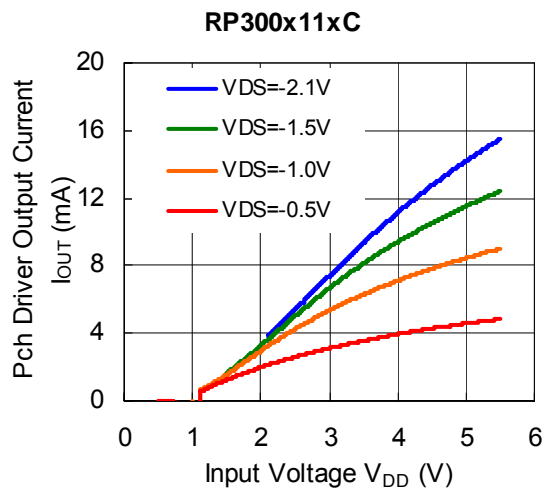
### 3) Nch Driver Output Current vs. Input Voltage

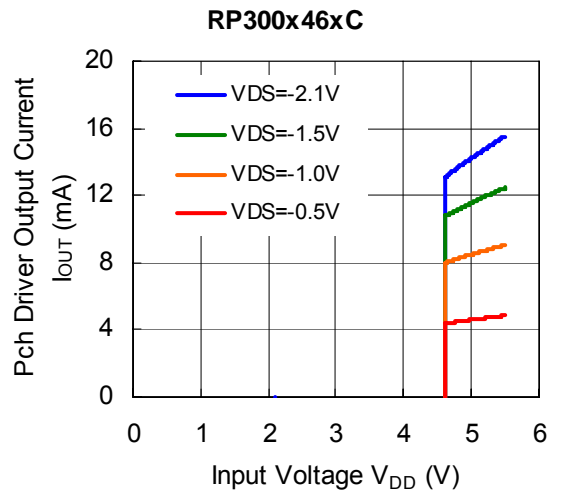
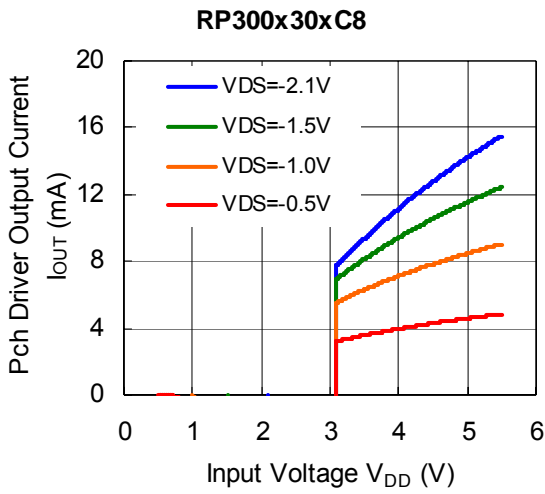


Nch Driver Inverting Output (custom IC)

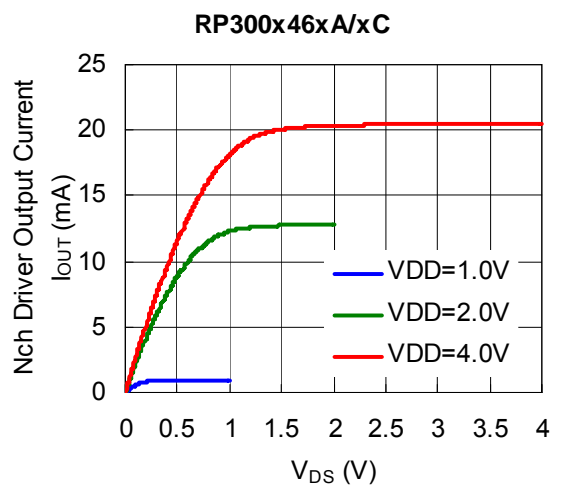
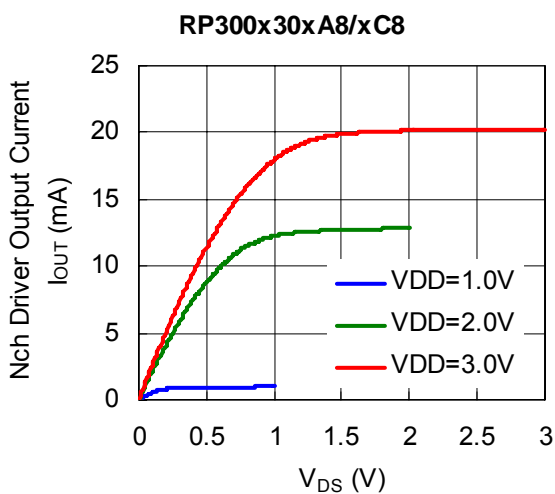
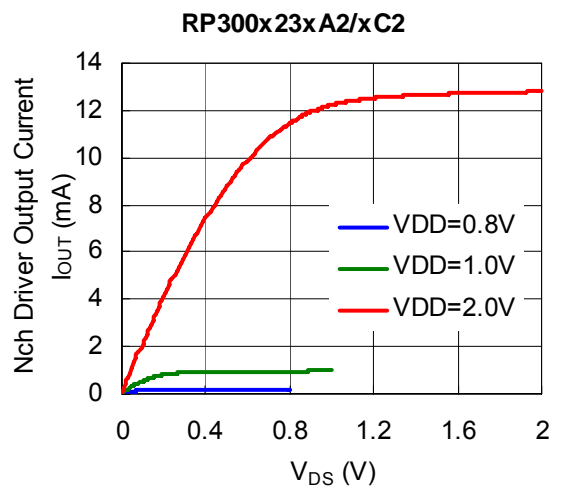
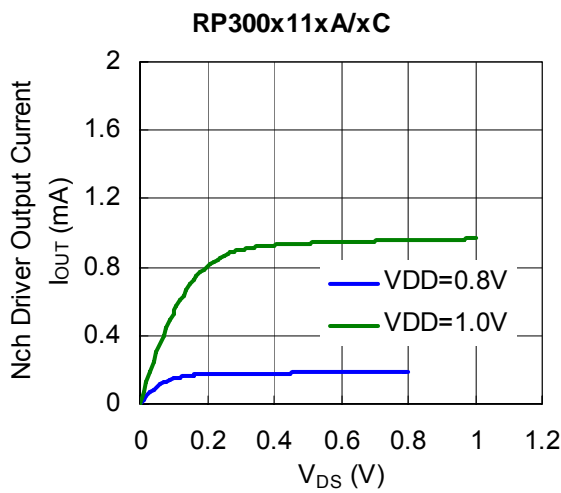


4) Pch Driver Output Current vs. Input Voltage

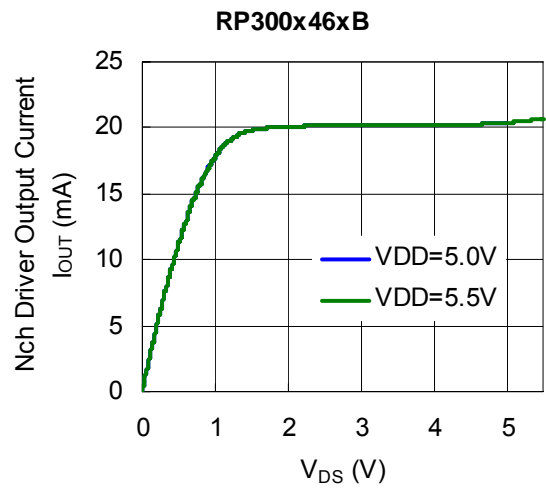
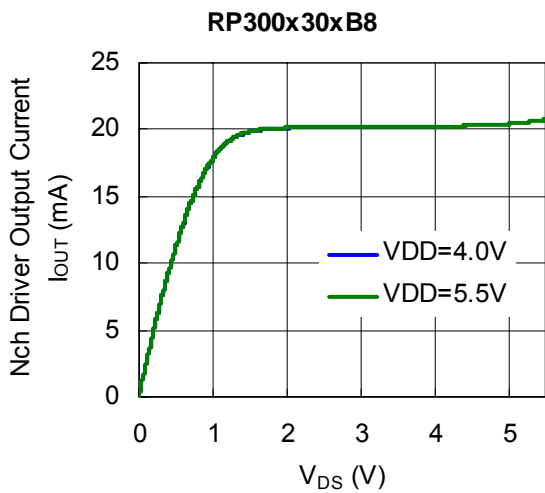
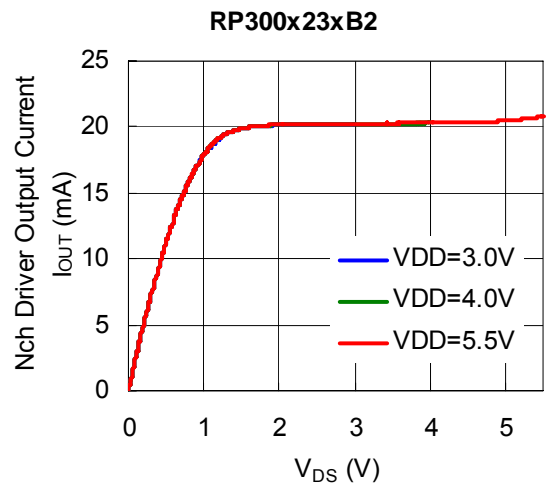
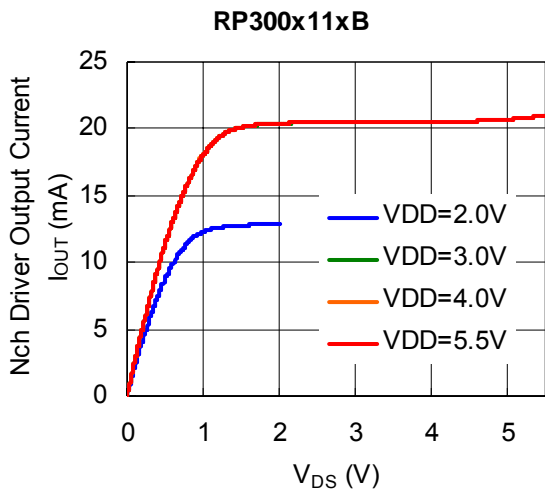




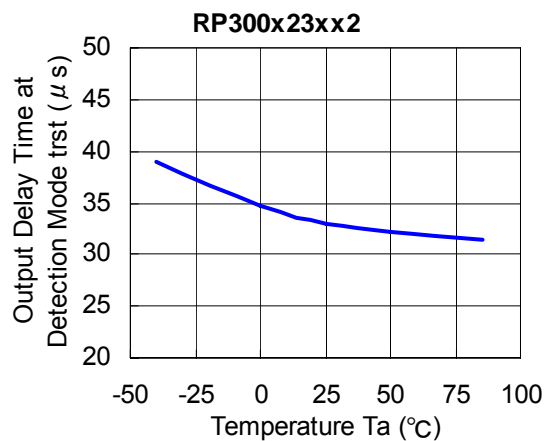
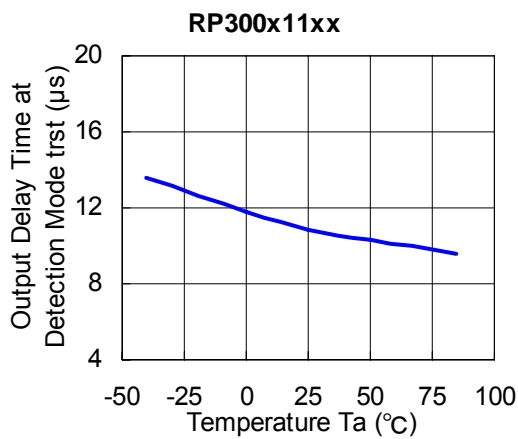
5) Nch Driver Output Current vs. V<sub>DS</sub>

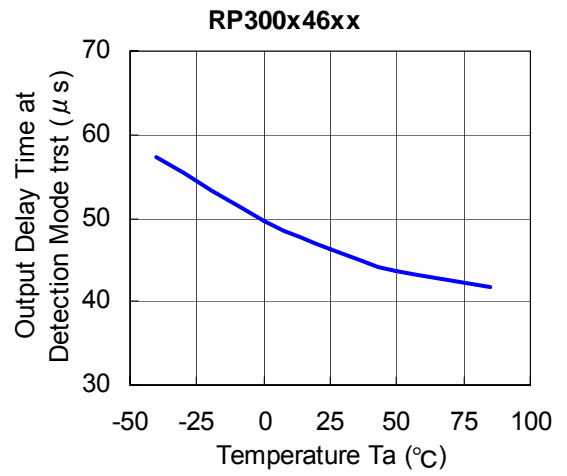
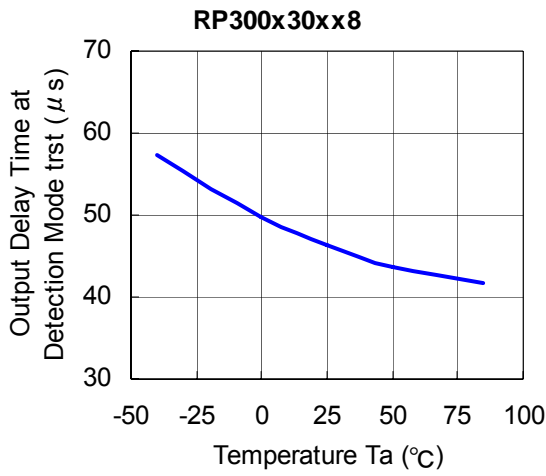


Nch Driver Inverting Output (custom IC)

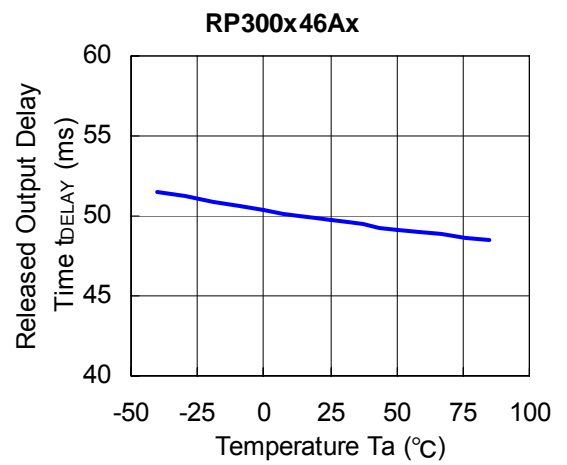
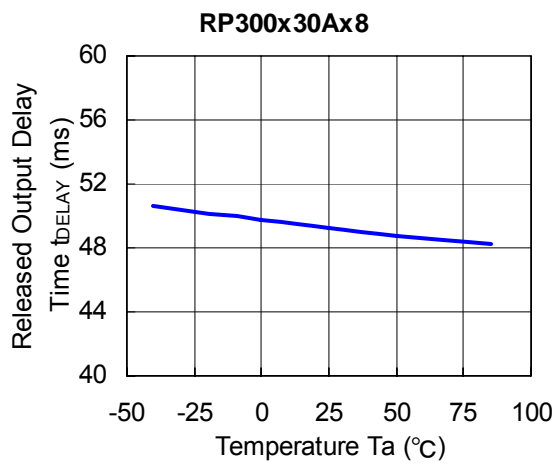
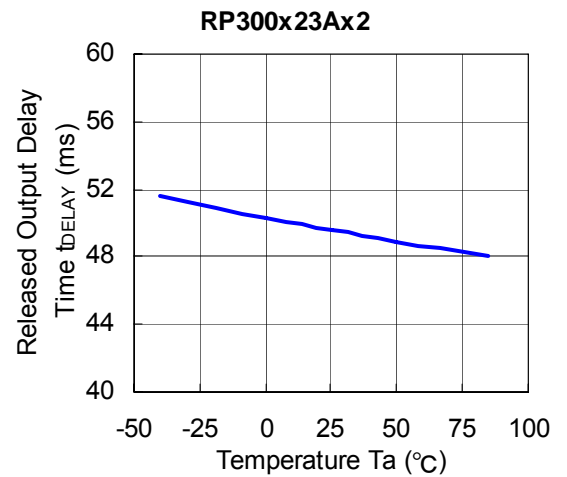
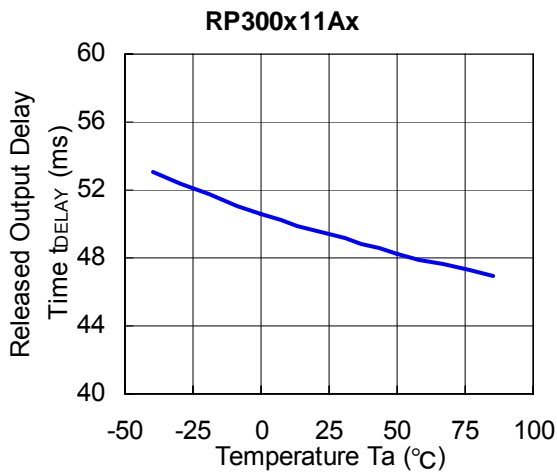


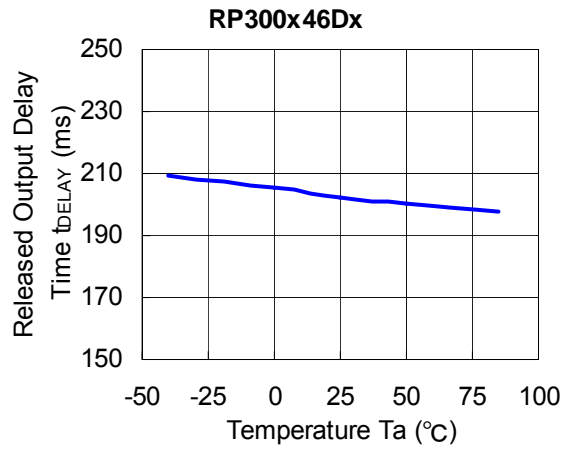
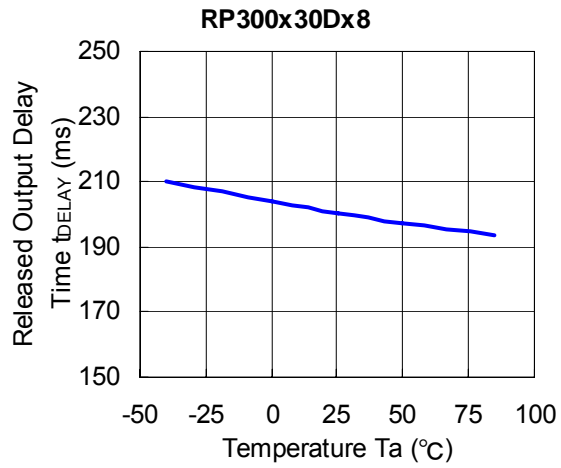
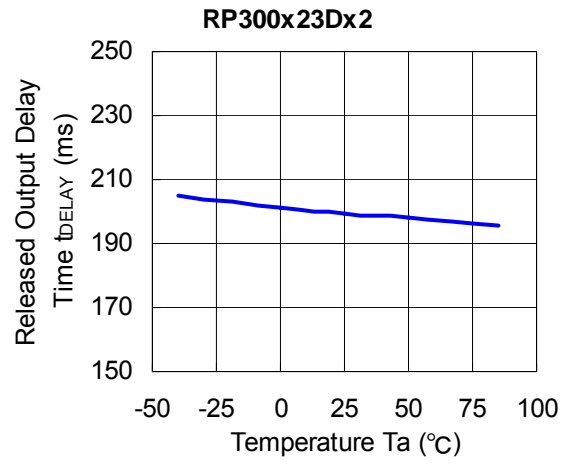
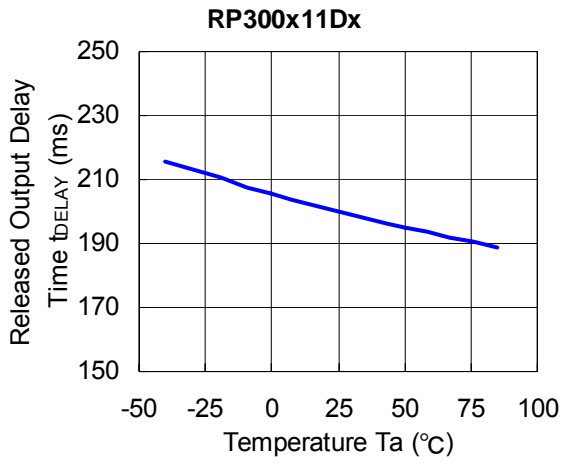
6) Output Delay Time at Detection Mode vs. Temperature





**7) Released Output Delay Time vs. Temperature**





## TECHNICAL NOTES

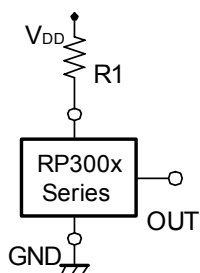


Figure 21.

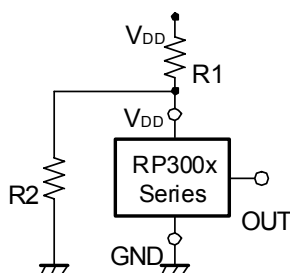


Figure 22.

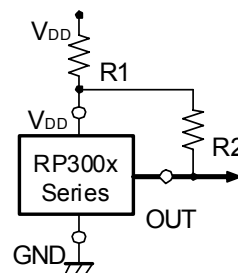


Figure 23.

- When using Nch open drain output products in circuits such as shown in Figure 21 and 22 with a large impedance ( $R1$ ) between the  $V_{DD}$  pin and  $V_{DD}$ , detector threshold level would shift by voltage dropdown caused by the supply current of the IC itself. Released voltage may also shift and delay time for start-up might be generated by this usage.
- If CMOS output products are used in circuits such as shown in Figure 21 and 22, output level could be unstable by shoot-through current which is generated at detector threshold level or at released voltage level, so please avoid this style of use.
- Connections such as shown in Figure 23, may cause an unstable operation of all output types, so please avoid this style of use.



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